



# WS Paste Flux



## Paste Flux

### Features:

- Excellent Wetting
- Wide Process Window
- Aqueous Wash with Water

### Description:

AIM WS Paste Flux is a water washable tacky/rework flux designed to wet virtually all solderable electronic surfaces, components, assemblies, and substrates. AIM WS Paste Flux may be used for general touch up or rework of printed circuit boards, and for attaching spheres to ball grid array (BGA) packages. WS Paste Flux offers excellent wetting activity whether reflowed by hand, hot-air rework stations, convection reflow ovens, or vapor phase soldering systems. WS Paste Flux is compatible with all tin-lead and lead-free alloys and can be used for a wide range of applications. WS Paste Flux can be brushed, dispensed, pin transferred, or stencil printed. WS Paste Flux is available in 10cc and 30 cc syringes.

### Flux Application:

When being used in rework, application should be limited to the area being worked. Application via dispense needle, brush or a cotton swab is recommended.

### Cleaning:

WS Paste Flux can be cleaned easily with normal tap water. Deionized water is recommended for the final rinse. A temperature of 38°C – 60°C (100°F - 150°F) is sufficient for removing residues. An in-line or other pressurized spray cleaning system is suggested, but not required.

### Handling and Storage:

- WS paste flux has a refrigerated shelf life of 1 year at 4°C (40°F) - 12°C (55°F) and 6 months at room temperature.
- Allow the paste flux to warm naturally to ambient temperature (2 hrs.) prior to use.
- Do not store new and used paste flux in the same container.

### Safety:

- Use with adequate ventilation and proper personal protective equipment.
- Refer to the accompanying **Material Safety Data Sheet** for any specific emergency information.
- Do not dispose of any hazardous materials in non-approved containers.

### Physical Properties:

| Parameter   | Value                      |
|-------------|----------------------------|
| J-STD-004   | ORM1                       |
| Acid Number | 53.89 mg KOH per gram flux |

| Parameter  | Value                |
|------------|----------------------|
| Viscosity  | Gel-like consistency |
| Appearance | Amber-light yellow   |

### Corrosion Testing:

| Parameter                            | Requirements      | Results         |
|--------------------------------------|-------------------|-----------------|
| Copper Mirror (24 hrs @ 25°C, 50%RH) | IPC-TM-650-2.3.32 | Medium          |
| Halide Test (Silver Chromate)        | IPC-TM-650-2.2.33 | Halides Present |

**Surface Insulation Resistance:**

| Reference                                       | Property                      | Pass-Fail Criteria              | Results |
|---|-------------------------------|---------------------------------|---------|
| IPC-TM-650<br>method 2.6.3.3<br>85°C / 85% R.H. | Control coupons               | >1E+9 Ω at 96 and 168 hrs       | Pass    |
|   | Sample coupons – pattern up   | >1E+8 Ω at 96 and 168 hrs       | Pass    |
|   | Sample coupons – pattern down | >1E+8 Ω at 96 and 168 hrs       | Pass    |
|   | Post-test visual inspection   | No dendrite growth or corrosion | Pass    |

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